Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HP Integrity rx2800 i4 Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm The server is configurable and may contain some of the following assemblies. Mod0 comes with systemboard, SAS backplane, front panel display and power supply backplane. AT104A HP rx2800 i4 Itanium Proc 4c 1.73GH/20MB AT105A HP rx2800 i4 Itanium Proc 8c 2.13GHz/24M AT106A HP rx2800 i4 Itanium Proc 8c 2.53GHz/32M AT138A HP rx2800 i4 Itanium Proc 4c 2.4GHz/32MB AM228A HP rx2800 i2 PCIe 3-Slot Riser Board AM245A HP rx2800 i2 PCIe 2-Slot Riser Board AT108A HP rx2800 i4 8GB(2x4GB) DDR3 Kit AT109A HP rx2800 i4 16GB(2x8GB) DDR3 Kit	Up to 54 when fully loaded (includes PCAs that comes with Mod0)

PSG instructions for this template are available at EL-MF877-01

	AT110A HP rx2800 i4 32GB(2x16GB) DDR3 Kit AT103A rx2800 i4 6-Slot Mem Exp Brd AM302A HP 146GB 15k SAS SFF 6GB DP Drive AM244A HP 300GB 10K SAS SFF 6GB DP Drive AM316A HP 450GB SAS 10Krpm SFF Hard Drive AM317A HP 600GB SAS 10Krpm SFF Hard Drive AT069A HP Integrity 900GB 10K SAS SFF HDD AT088A HP Integrity 200GB SAS 6Gb SFF SLC SSD AT089A HP Integrity 400GB SAS 6Gb SFF SLC SSD AD333A HP Integrity 146GB 10k SAS Drive AT086A HP Integrity 300GB 15K SAS SFF HDD AM242A HP Slimline DVD-ROM Optical Drive AM243A HP Slimline DVD+RW Optical Drive AD221A HP PCIe 1p 4GB FC and 1p 1000BT Adapter AD222A HP PCIe 2p 4GB FC and 2p 1000BT Adapter AD393A HP PCIe 2p 4GB FC and 2p 1000BSX Adptr AT094A HP PCIe 2p 8Gb FC and 2p 1/10GbE Adapter AH423A HP Integrity rx2800 i2 2D Graphics Adptr AT083A HP Integrity PCIe 2-port 4X QDR IB HCA AT118A HP Integrity NC552SFP 2P 10GbE Adapter AT111A HP Integrity CN1100E PCIe 2-port CNA AH400A HP PCIe 1-port 8Gb FC SR (Qlogic) HBA AH401A HP PCIe 2-port 8Gb FC SR (Qlogic) HBA AH402A HP PCIe 1-port 8Gb FC SR (Emulex) HBA AH403A HP PCIe 2-port 8Gb FC SR (Emulex) HBA AM311A HP Integrity PCIe 2p P411/256MB SAS Ctlr AM312A HP Integrity SA 812/1GB PCIe SAS Ctlr AM225A HP Integrity 10GbE-SR 2p PCIe Adapter AM232A HP Integrity 10GbE-LR 2p PCIe	

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	Adapter AM233A HP Integrity 10GbE-Cu 2p PCIe Adapter AD337A HP PCIe 2-port 1000Base-T Card AD338A HP PCIe 2-port 1000Base-SX Card AD339A HP PCIe, 1000Base-T, 4p Adptr AM252A HP rx2800 i2 512MB FBWC Kit AT133A rx2800 i4 Power Supply AM237A HP rx2800 i2 Trusted Platform Module Kit	
Batteries	All types including standard alkaline and lithium coin or button style batteries AM252A HP rx2800 i2 512MB FBWC Kit	Up to 2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	1. Fan, Cage , IEC PN : 6051B0501301 , HP PN : NA 2. Air_baffle , IEC PN : 6051B0500901 , HP PN : AH395-3401A	2
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

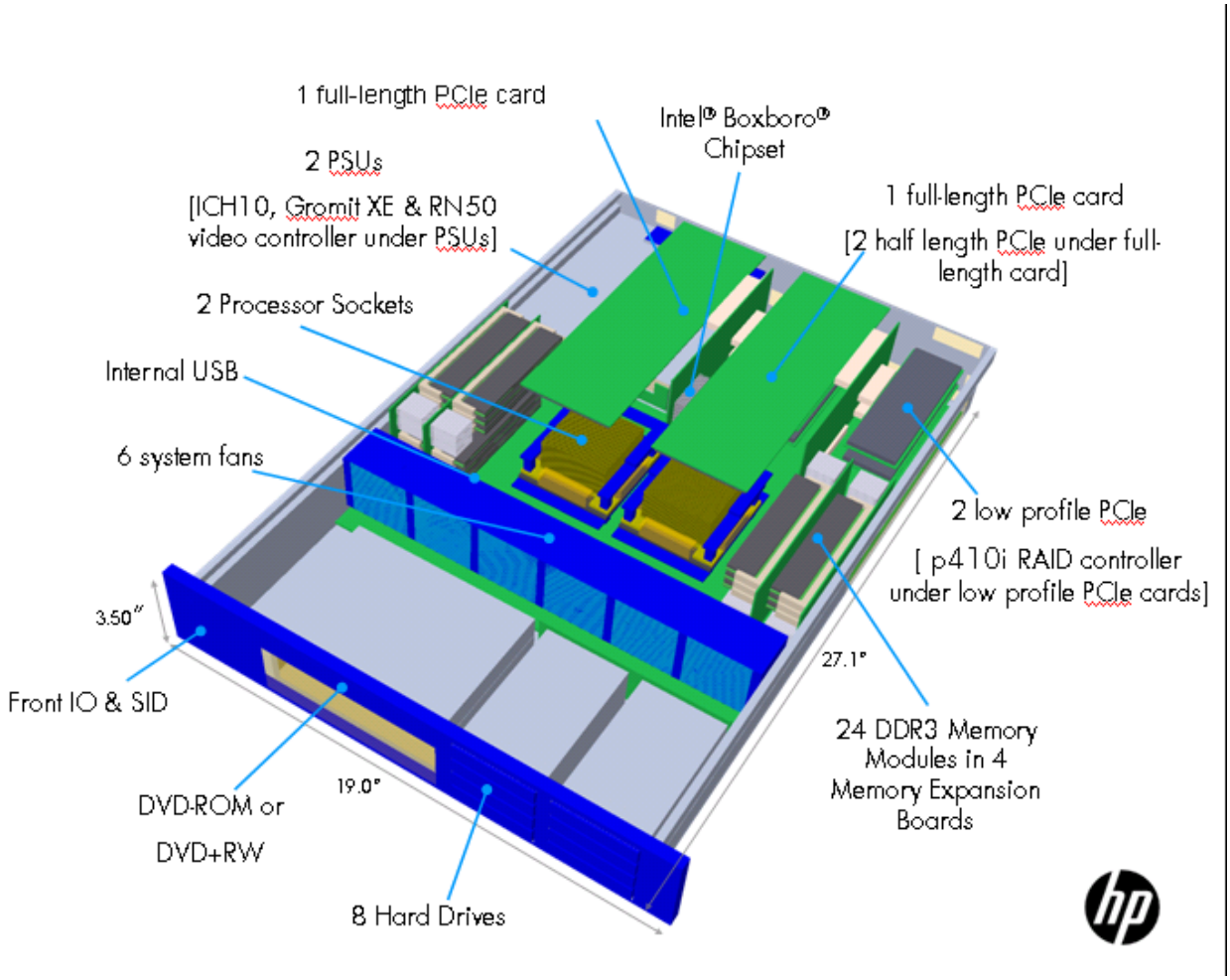
Tool Description	Tool Size (if applicable)
Torx screw driver T10/T5	T10/T5

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. All panels and assemblies can be removed from the Mode assemby by either Torx or screwdriver.
2. Once removed from Mod0, all PCAs can be removed from frame assembly by use of Torx or screwdriver.
3. Removing battery on system by finger.
4.
5.
6.
7.
8.
9.
10.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



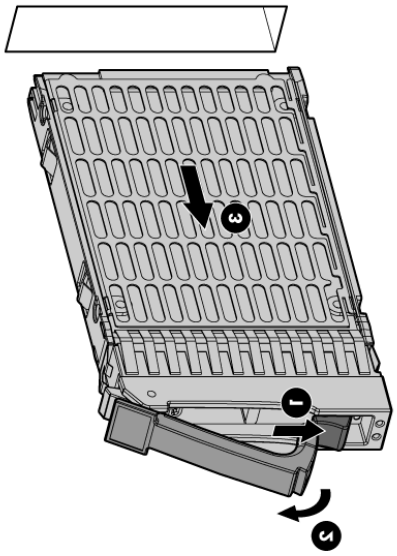
The system should be shut down before any disassembly is carried out.

Removal of DIMMS

1. Remove the Memory Riser Boards from the Chassis.
2. Push the memory latches outside to disengage the memory form the slots
3. Pull the memory out of the slot by the sides.

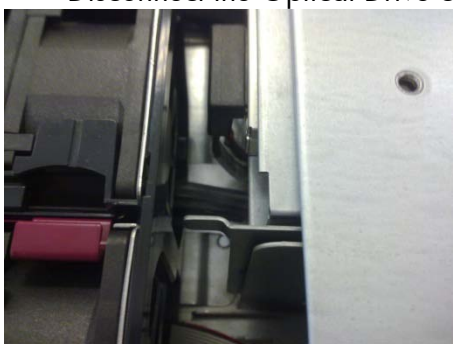
Removal of HDD Drives

1. Press the release button.
2. Open the ejector lever.
3. Slide the disk drive out of the drive cage.



Removal of Optical Drives

1. Disconnect the Optical Drive cable (found in Mod0) to the Optical Drive.



2. Push out the Optical Drive from the inside of the system

Removal of IO Cards

1. Unfasten the blue Thumbscrew

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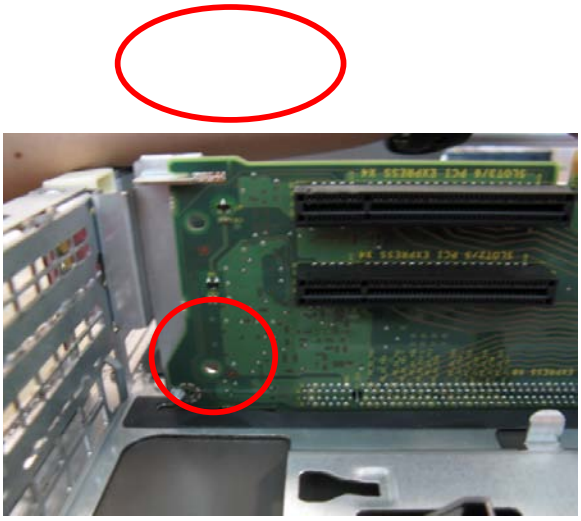
2. Dislodge the top and bottom latches.

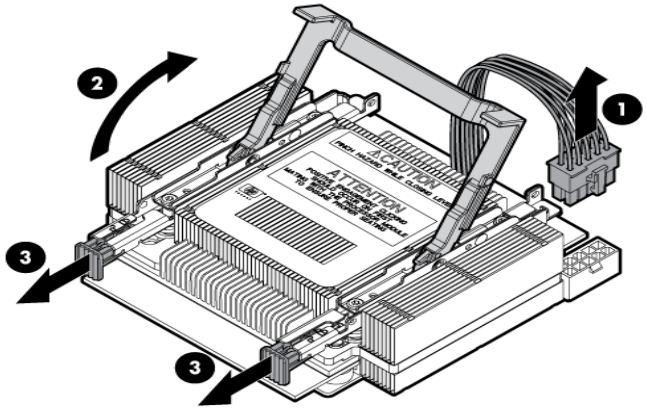


Removal of CPU

1. Rotate the processor locking handle up and back until it reaches a hard stop (see 2 below).

   WARNING! The heatsink locking lever can constitute a pinch hazard; keep your hands on top of the lever during installation to avoid personal injury.

2. Pull both plastic tabs out (see 3 below).



3. Lift the processor and heatsink off of the socket, pulling straight up.

Removal of Battery